

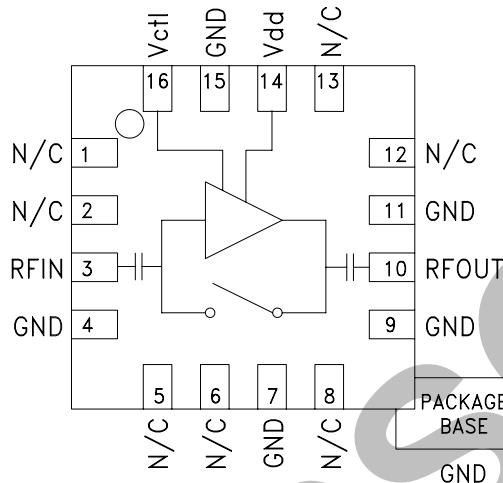


## *Typical Applications*

The HMC605LP3 / HMC605LP3E is ideal for:

- Wireless Infrastructure
- Customer Premise Equipment
- Fixed Wireless
- WiMAX & WiBro
- Tower Mounted Amplifiers

## ***Functional Diagram***



## Features

Noise Figure: 1.1 dB

Output IP3: +31 dBm

Gain: 20 dB

## Low Loss & Failsafe Bypass Path

Single Supply: +3V or +5V

50 Ohm Matched Output/Input

## ***General Description***

The HMC605LP3 / HMC605LP3E are versatile, high dynamic range GaAs MMIC Low Noise Amplifiers that integrate a low loss LNA bypass path on the IC. The amplifier is ideal for WiBro & WiMAX receivers operating between 2.3 and 2.7 GHz and provides 1.1 dB noise figure, 20 dB of gain and +31 dBm output IP3 from a single supply of +5V @ 74 mA. Input and output return losses are 14 and 15 dB respectively with no external matching components required. A single control line (Vctl) is used to switch between LNA mode and a low 2 dB loss bypass mode and reduces the current consumption to 10  $\mu$ A. The HMC605LP3 is failsafe and will default to the bypass mode with no DC power applied.

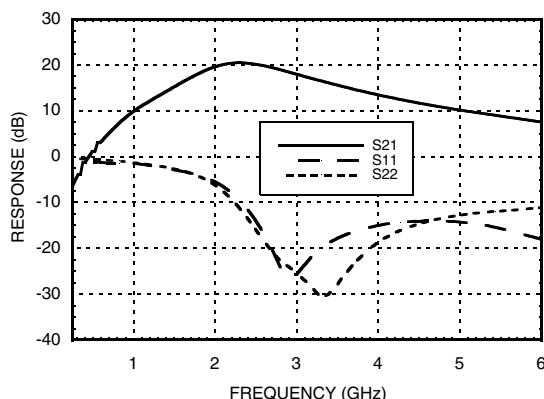
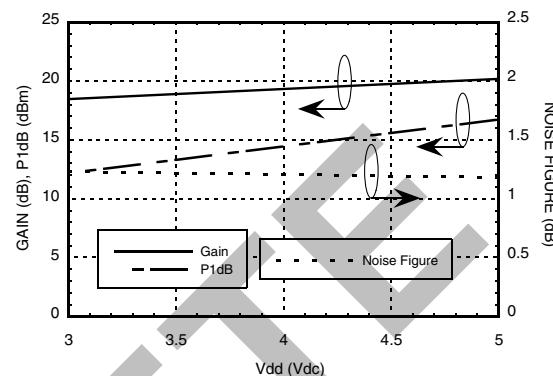
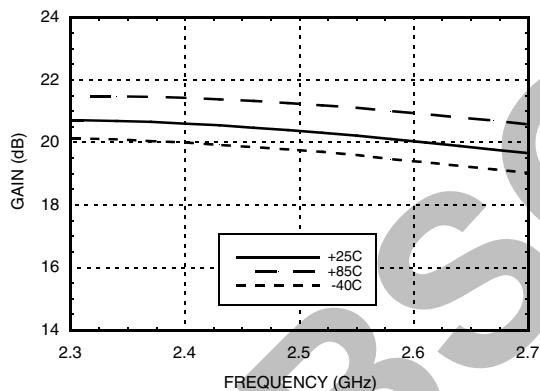
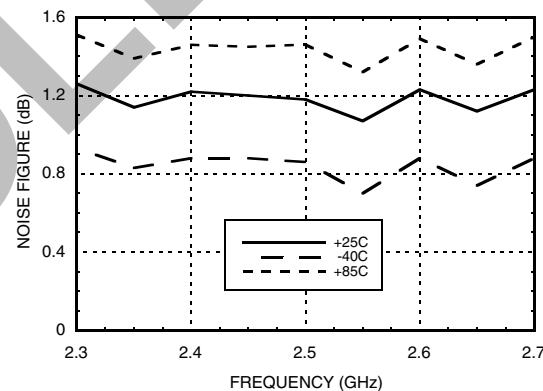
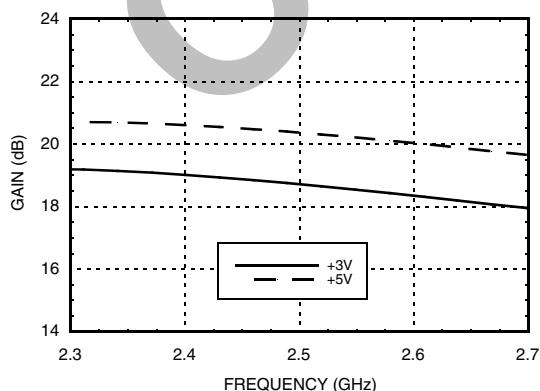
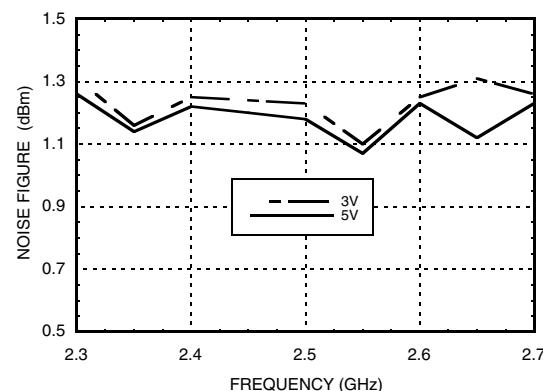
### **Electrical Specifications. $T_c = +25^\circ C$ . $Vdd = 5V$**

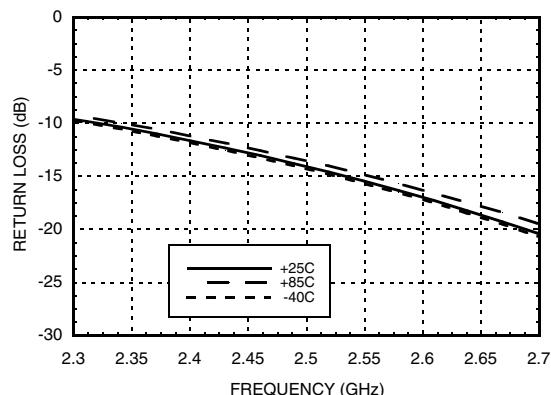
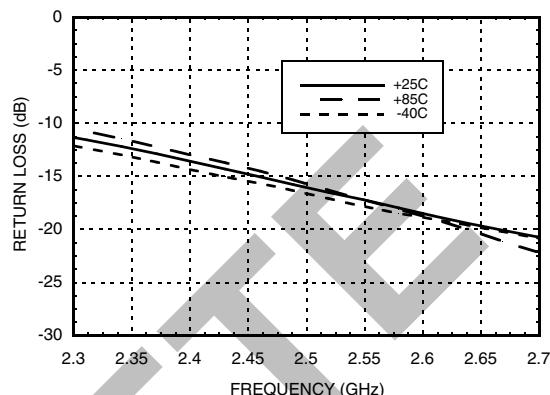
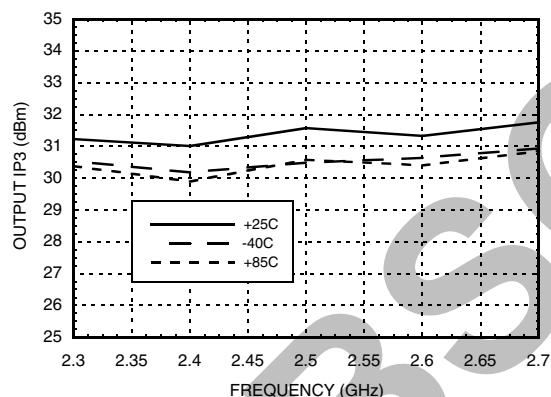
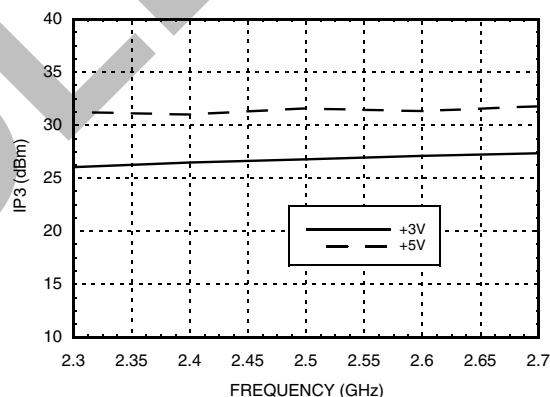
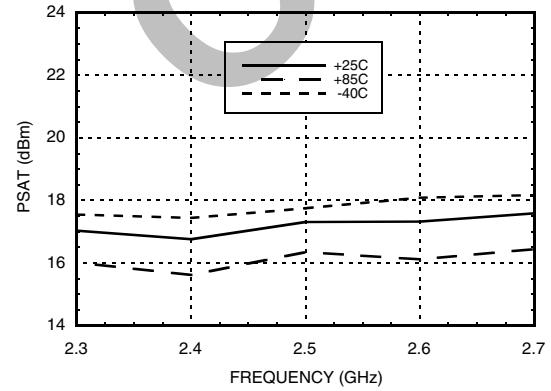
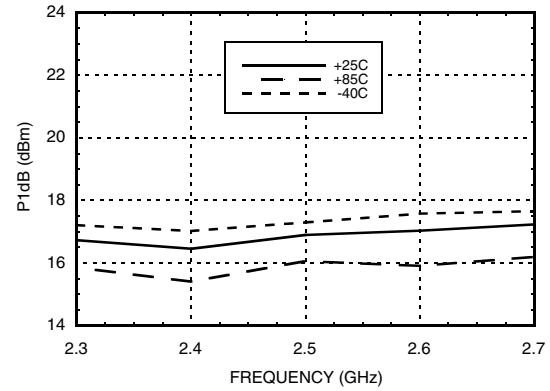
Parameter	LNA Mode			Bypass Mode			Units
	Min.	Typ.	Max.	Min.	Typ.	Max.	
Frequency Range	2.3 - 2.7			2.3 - 2.7			GHz
Gain	17.5	20.5		-3.0	-2.0		dB
Gain Variation Over Temperature		0.012			0.002		dB / °C
Noise Figure		1.1	1.3				dB
Input Return Loss		14			13		dB
Output Return Loss		15			13		dB
Reverse Isolation		33					dB
Power for 1dB Compression (P1dB) <sup>[1]</sup>		17			14		dBm
Third Order Intercept (IP3) <sup>[2]</sup>		31			23		dBm
Supply Current (Idd)		74	90		0.01		mA
Switching Speed	LNA Mode to Bypass Mode	-			6.0		ns
		60			-		ns

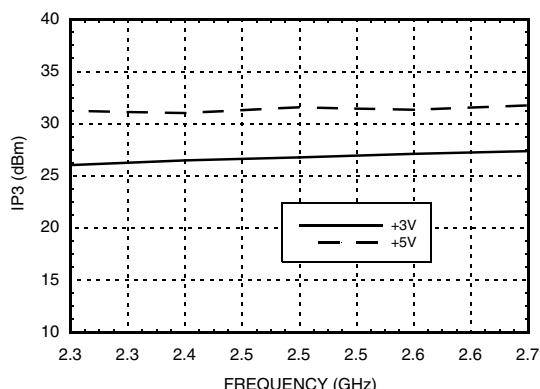
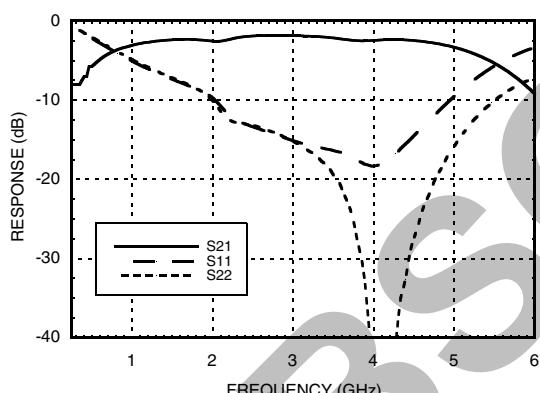
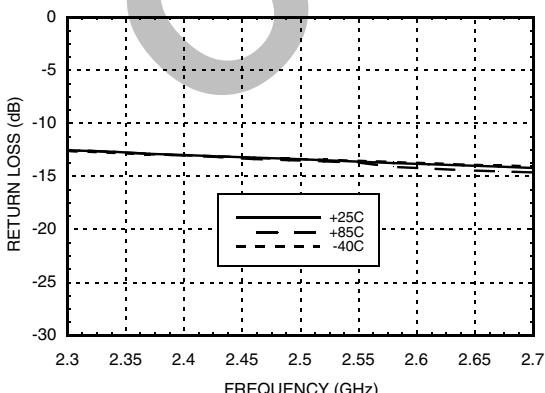
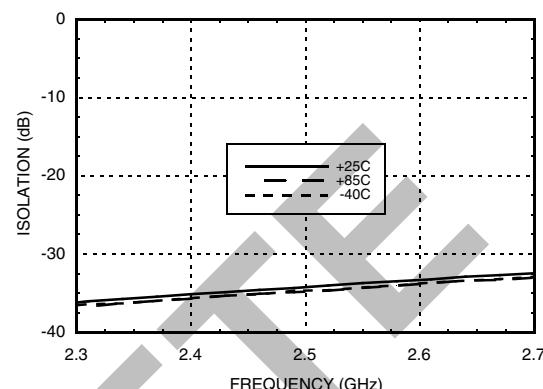
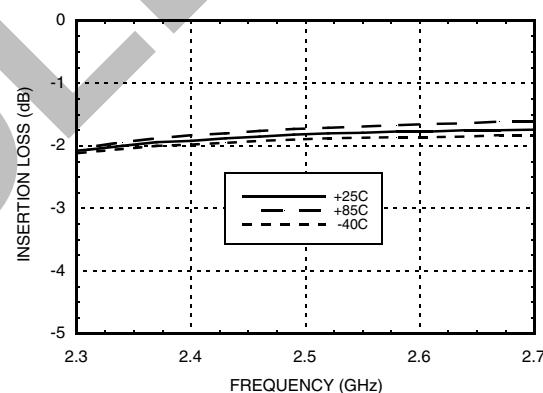
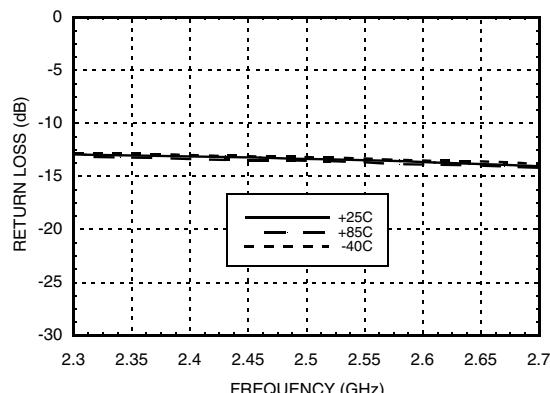
[1] R1dB and IIP3 is referenced to REQUIT for LNA mode and to REIN for Bypass Mode.

[2] For LNA Mode: Input tone power is -20 dBm/tone at 1 MHz tone spacing.

For ENA Mode: Input tone power is -20 dBm/tone at 1 MHz tone spacing  
For Bypass Mode: Input tone power is 0 dBm/tone at 1 MHz tone spacing

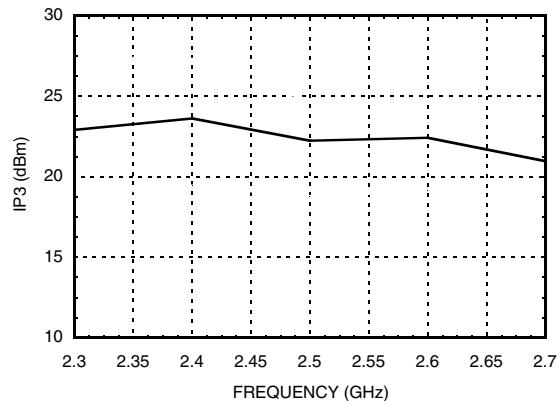

**GAAS PHEMT MMIC LOW NOISE  
AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz**
**LNA Broadband Gain & Return Loss**

**LNA Gain, Noise Figure &  
Power vs. Supply Voltage @ 2.5 GHz**

**LNA Gain vs. Temperature**

**LNA Noise Figure vs. Temperature**

**LNA Gain vs. Vdd**

**LNA Noise Figure vs. Vdd**



**GAAS PHEMT MMIC LOW NOISE  
AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz**
**LNA Input Return Loss vs. Temperature**

**LNA Output Return Loss vs. Temperature**

**LNA Output IP3 vs. Temperature**

**LNA Output IP3 vs. Vdd**

**LNA Psat vs. Temperature**

**LNA Output P1dB vs. Temperature**



**GAAS PHEMT MMIC LOW NOISE  
AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz**
**LNA Output P1dB vs. Vdd**

**Bypass Mode  
Broadband Gain & Return Loss**

**Bypass Mode  
Input Return Loss vs. Temperature [1]**

**LNA Reverse Isolation vs. Temperature**

**Bypass Mode  
Insertion Loss vs. Temperature**

**Bypass Mode  
Output Return Loss vs. Temperature [1]**


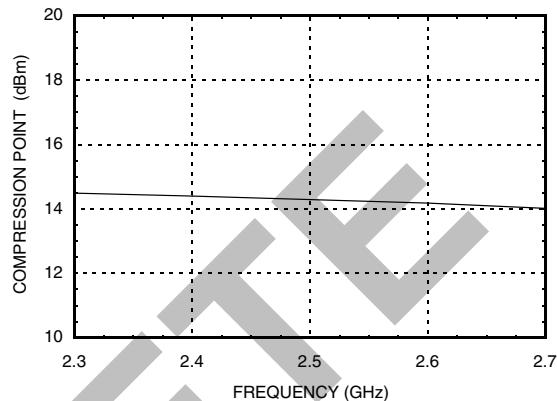


**Bypass Mode**  
*Input IP3 vs. Frequency*



**GAAS PHEMT MMIC LOW NOISE  
AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz**

**Bypass Mode**  
*Input P1dB vs. Frequency*




**GAAS PHEMT MMIC LOW NOISE  
AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz**
**Absolute Maximum Ratings**

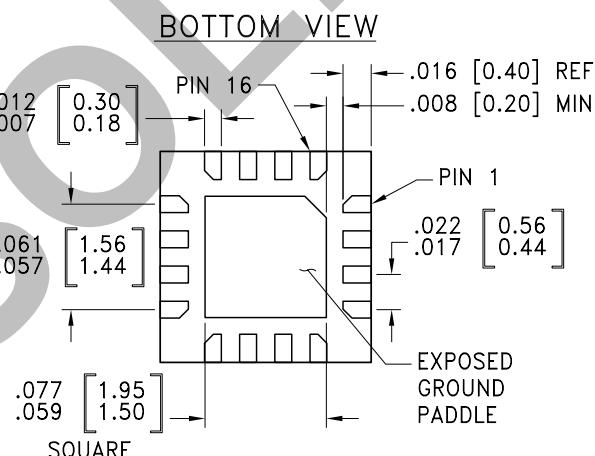
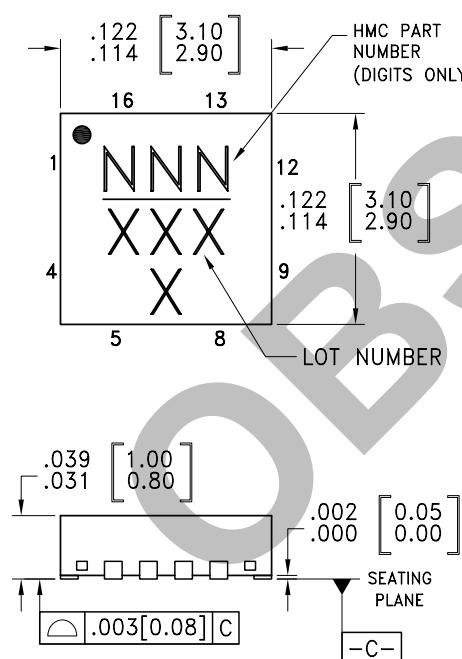
Drain Bias Voltage (Vdd)	+8 Vdc
RF Input Power (RFIN) (Vdd = +5.0 Vdc)	LNA Mode +22 dBm Bypass Mode +30 dBm
Channel Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 15.85 mW/°C above 85 °C)	1.03 mW
Thermal Resistance (channel to ground paddle)	63.08 °C/W
Storage Temperature	-65 to +150° C
Operating Temperature	-40 to +100° C

**Typical Supply Current vs. Vdd**

Vdd (Vdc)	Idd (mA)
+3.0	28
+5.0	74

**Truth Table**

LNA Mode	Vctl= Vdd ± 0.3V
Bypass Mode	Vctl= 0 ± 0.3V


**ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS**
**Outline Drawing**

**NOTES:**

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.  
PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

**Package Information**

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking <sup>[3]</sup>
HMC605LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 <sup>[1]</sup>	605 XXXX
HMC605LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 <sup>[2]</sup>	605 XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

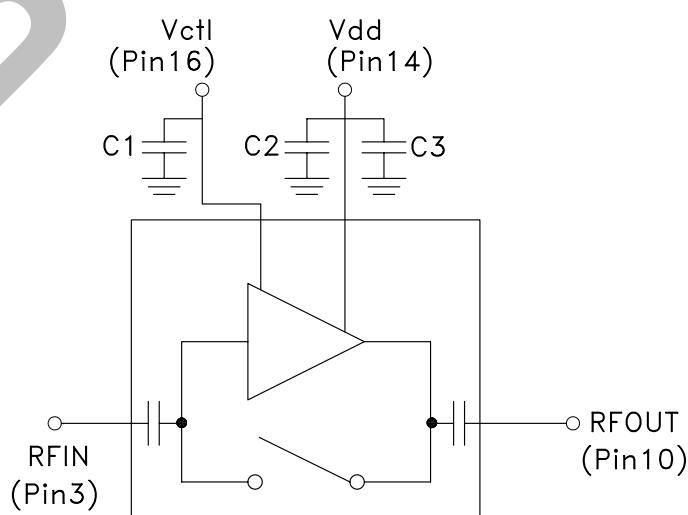
[3] 4-Digit lot number XXXX

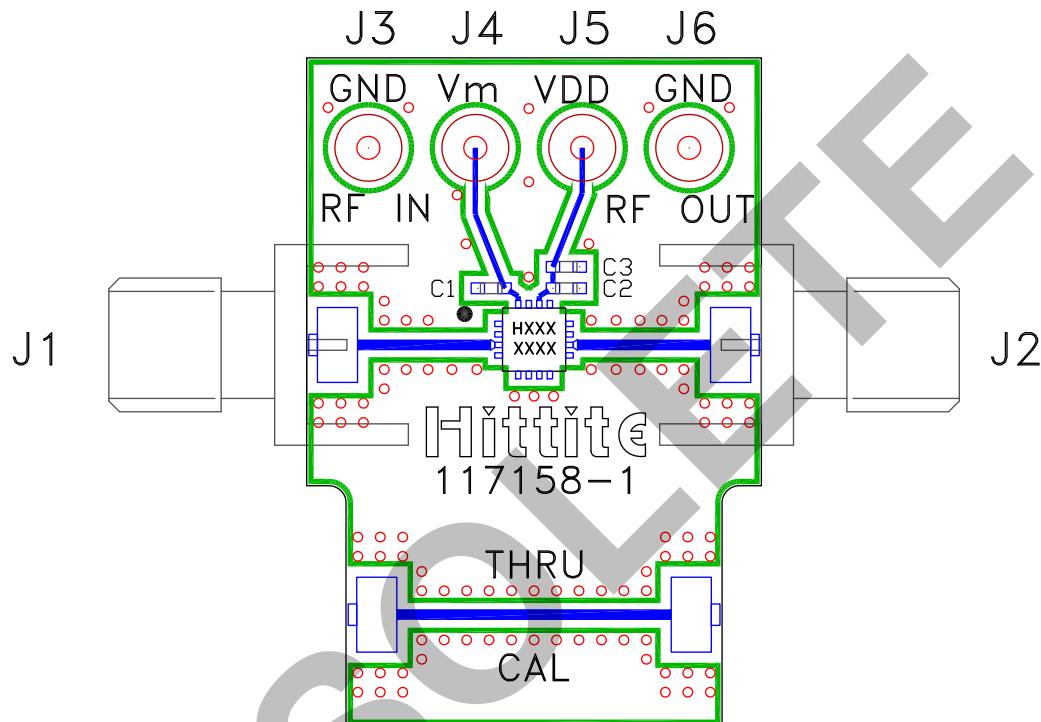

**GAAS PHEMT MMIC LOW NOISE  
AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz**
**Pin Descriptions**

Pin Number	Function	Description	Interface Schematic
1, 2, 5, 6, 8, 12	N/C	No connection necessary. These pins may be connected to RF/DC ground.	
3	RFIN	This pin is AC coupled and matched to 50 Ohms.	RFIN
4, 7, 9, 11, 15	GND	These pins must be connected to RF/DC ground.	GND
10	RFOUT	This pin is AC coupled and matched to 50 Ohms.	RFOUT
14	Vdd	Power supply voltage. Bypass capacitors are required. See application circuit.	Vdd
16	Vctl	LNA/Bypass Mode Control Voltage. See truth table.	Vctl

**Application Circuit**

Components	Value
C1, C2	100pF
C3	10KpF




**GAAS PHEMT MMIC LOW NOISE  
AMPLIFIER w/ BYPASS MODE, 2.3 - 2.7 GHz**
**Evaluation PCB**

**List of Materials for Evaluation PCB 117160<sup>[1]</sup>**

Item	Description
J1 - J2	PCB Mount SMA RF Connector
J3 - J6	DC Pin
C1, C2	100 pF Capacitor, 0402 Pkg.
C3	10 KpF Capacitor, 0402 Pkg.
U1	HMC605LP3 / 605LP3E Amplifier
PCB <sup>[2]</sup>	117158 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

# Mouser Electronics

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